



Test Report issued under the responsibility of:



TEST REPORT
IEC 60269-4
Low-voltage fuses
Part 4: Supplementary requirements for fuse-links for the protection of semiconductor devices

Report Number: 03601-A-24CB0183-S
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Total number of pages..... 30

Name of Testing Laboratory preparing the Report.....: Suzhou Electrical Apparatus Science Research Institute Co., Ltd.(EETI)

Applicant's name.....: Zhejiang Tengen Electric Co., Ltd.
Address: Sulv Industrial Area, Liusi Town, Yueqing City, Zhejiang Province, P.R.China

Test specification:

Standard: IEC 60269-4:2009, IEC 60269-4:2009/AMD1:2012, IEC 60269-4:2009/AMD2:2016
see also IEC 60269-1:2006, IEC 60269-1:2006/AMD1:2009, IEC 60269-1:2006/AMD2:2014

Test procedure: CB Scheme

Non-standard test method: N/A

TRF template used: IECEE OD-2020-F1:2022, Ed.1.5

Test Report Form No.: IEC60269_4D

Test Report Form(s) Originator: CQC

Master TRF.....: Dated 2023-08-17

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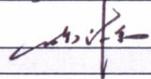
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Test item description	Fuse for the protection of semiconductor equipment	
Trade Mark	TENGEN	
Manufacturer	Zhejiang Tengen Electric Co.,Ltd. Sulv Industrial Area, Liushi Town, Yueqing City, Zhejiang Province, P.R.China	
Model/Type reference	TGRS3Z-300CQ	
Ratings	See Page 7	
Responsible Testing Laboratory (as applicable), testing procedure and testing location(s):		
<input checked="" type="checkbox"/>	CB Testing Laboratory:	Suzhou Electrical Apparatus Science Research Institute Co., Ltd.(EETI)
	Testing location/ address	No.7 Yonghe Street, Binhe Road, New District, Suzhou, China
	Tested by (name, function, signature)	Fang Gang (Team leader) 
	Approved by (name, function, signature) ..	Chen Yuan(Supervisor) 
<input type="checkbox"/>	Testing procedure: CTF Stage 1:	
	Testing location/ address	
	Tested by (name, function, signature)	
	Approved by (name, function, signature) ..	
<input type="checkbox"/>	Testing procedure: CTF Stage 2:	
	Testing location/ address	
	Tested by (name + signature)	
	Witnessed by (name, function, signature) . :	
	Approved by (name, function, signature) .. ✓	
<input type="checkbox"/>	Testing procedure: CTF Stage 3:	
<input type="checkbox"/>	Testing procedure: CTF Stage 4:	
	Testing location/ address	
	Tested by (name, function, signature)	
	Witnessed by (name, function, signature) . :	
	Approved by (name, function, signature) ..	
	Supervised by (name, function, signature) :	